



Docket No.: M4065.0248/P248-C
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Allen McTeer

Application No.: 10/656,182

Art Unit: 2815

Filed: September 8, 2003

Examiner: E. Lee

For: A MULTI-LAYERED COPPER BOND PAD
FOR AN INTEGRATED CIRCUIT

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated September 8, 2004 (Paper No. 20040717), please amend the above-identified U.S. patent application as follows:

Amendments to the specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Amendments to the Drawings begin on page 7 of this paper.

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Reply to Office Action dated September 8, 2004

Remarks begin on page 8 of this paper.